

To our customers,

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April 1<sup>st</sup>, 2010  
Renesas Electronics Corporation

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# User's Manual

# QB-78K0RKX3

## In-Circuit Emulator

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### Target Devices

**78K0R/KE3**

**78K0R/KF3**

**78K0R/KG3**

**78K0R/KH3**

**78K0R/KJ3**

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## General Precautions for Handling This Product

### 1. Circumstances not covered by product guarantee

- If the product was disassembled, altered, or repaired by the customer
- If it was dropped, broken, or given another strong shock
- Use at overvoltage, use outside guaranteed temperature range, storing outside guaranteed temperature range
- If power was turned on while connection to the AC adapter, USB interface cable, or target system was in an unsatisfactory state
- If the cable of the AC adapter, the USB interface cable, the emulation probe, or the like was bent or pulled excessively
- If an AC adapter other than the supplied product was used
- If the product got wet
- If this product is connected to the target system when there is a potential difference between the GND of this product and GND of the target system.
- If the connectors or cables are plugged/unplugged while this product is in the power-on state.
- If excessive load is applied to the connectors or sockets (As for handling, please see **2.5 Mounting and Connecting Connectors**).
- If a metal part of the power switch, cooling fan, or another such part comes in contact with an electrostatic charge.
- If the product is used or stored in an environment where an electrostatic or electrical noise is likely to occur.

### 2. Safety precautions

- If used for a long time, the product may become hot (50°C to 60°C). Be careful of low temperature burns and other dangers due to the product becoming hot.
- Be careful of electrical shock. There is a danger of electrical shock if the product is used as described above in **1. Circumstances not covered by product guarantee**.
- The AC adapter supplied with the product is exclusively for this product, so do not use it with other products.

## INTRODUCTION

**Readers** This manual is intended for users who wish to perform debugging using the QB-78K0RKX3. The readers of this manual are assumed to be familiar with the device functions and usage, and to have knowledge of debuggers.

**Purpose** This manual is intended to give users an understanding of the basic specifications and correct usage of the QB-78K0RKX3.

**Organization** This manual is divided into the following sections.

- General
- Setup procedure
- Settings at product shipment
- Cautions
- Characteristics of target interface

**How to Read This Manual** It is assumed that the readers of this manual have general knowledge in the fields of electrical engineering, logic circuits, and microcontrollers.

This manual describes the basic setup procedures and how to set switches.

To understand the overall functions and usages of the QB-78K0RKX3

→ Read this manual in the order of the **CONTENTS**. The mark “<R>” shows major revised points. The revised points can be easily searched by copying an “<R>” in the PDF file and specifying it in the “Find what:” field.

To know the manipulations, command functions, and other software-related settings of the QB-78K0RKX3

→ See the user’s manual of the debugger (supplied with the QB-78K0RKX3) to be used.

### Conventions

**Note:** Footnote for item marked with **Note** in the text

**Caution:** Information requiring particular attention

**Remark:** Supplementary information

Numeric representation: Binary ... xxxx or xxxxB

Decimal ... xxxx

Hexadecimal ... xxxxH

Prefix indicating power of 2

(address space, memory

capacity):

K (kilo):  $2^{10} = 1,024$

M (mega):  $2^{20} = 1,024^2$

## Terminology

The meanings of the terms used in this manual are described in the table below.

Term	Meaning
Target device	This is the device to be emulated.
Target system	This is the system to be debugged. This includes the target program and the hardware provided by the user.
78K0R/Kx3	Generic name indicating 78K0R/KE3, 78K0R/KF3, 78K0R/KG3, 78K0R/KH3 and 78K0R/KJ3.
IECUBE™	Generic name for NEC Electronics' high-performance/compact in-circuit emulator.

## Related Documents

Please use the following documents in conjunction with this manual.

The related documents listed below may include preliminary versions. However, preliminary versions are not marked as such.

<R>

## Documents Related to Development Tools (User's Manuals)

Document Name		Document Number
QB-78K0RKX3 In-Circuit Emulator		This manual
RA78K0R Ver. 1.20 Assembler Package	Operation	U18547E
	Language	U18546E
CC78K0R Ver. 2.00 C Compiler	Operation	U18549E
	Language	U18548E
ID78K0R-QB Ver. 3.20 Integrated Debugger	Operation	U17839E
PM+ Ver. 6.30 Project Manager		U18416E

**Caution** The related documents listed above are subject to change without notice. Be sure to use the latest version of each document for designing, etc.

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## CHAPTER 1 GENERAL

The QB-78K0RKX3 is an in-circuit emulator for emulating the 78K0R/Kx3.

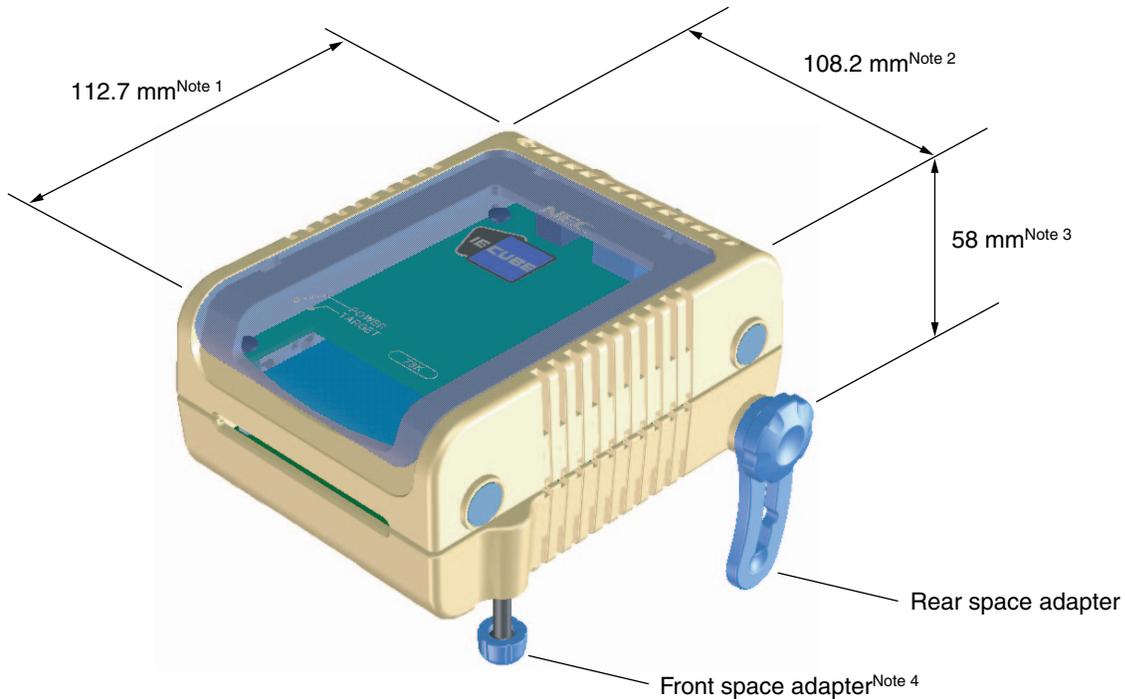
Hardware and software can be debugged efficiently in the development of systems in which the 78K0R/Kx3 is used. This manual describes basic setup procedures, hardware specifications, system specifications, and how to set switches.

1.1 Hardware Specifications

Table 1-1. QB-78K0RKX3 Hardware Specifications

Parameter		Specification	
Target device		78K0R/KE3, 78K0R/KF3, 78K0R/KG3, 78K0R/KH3, 78K0R/KJ3	
Operating voltage		1.8 to 5.5 V	
Operating frequency		High-speed system clock $2.7\text{ V} \leq V_{DD} \leq 5.5\text{ V}$ : 2 to 20 MHz $1.8\text{ V} \leq V_{DD} \leq 2.7\text{ V}$ : 2 to 5 MHz	
		Internal high-speed oscillation clock	An 8 MHz clock is supplied from the oscillator in the QB-78K0RKX3
		Internal low-speed oscillation clock	A 240 kHz clock is supplied from the oscillator in the QB-78K0RKX3
		Subsystem clock	A 32.768 kHz clock is supplied from the oscillator in the QB-78K0RKX3
Operating temperature range		0 to 40°C (No condensation)	
Storage temperature range		-15 to 60°C (No condensation)	
External dimensions		See figure below	
Power consumption	AC adapter for QB-78K0RKX3	Output: DC15 V, 1 A Input: AC100 to 240 V	
	Target system power supply	Voltage: 1.8 to 5.5 V Current: approx. 4.1 mA MAX.	
Weight		Approx. 400 g	
Host interface		USB interface (1.1, 2.0)	

<R>



- Notes**
1. Does not include projection of power switch
  2. Includes projection of screw that fixes rear space adapter
  3. Rear space adapter can adjust the height from 30 mm (longest) to 0 mm (shortest)
  4. Front space adapter can adjust the height from 20 mm (longest) to 5 mm (shortest)

## 1.2 System Specifications

This section shows the QB-78K0RKX3 system specifications.

**Table 1-2. QB-78K0RKX3 System Specifications (1/2)**

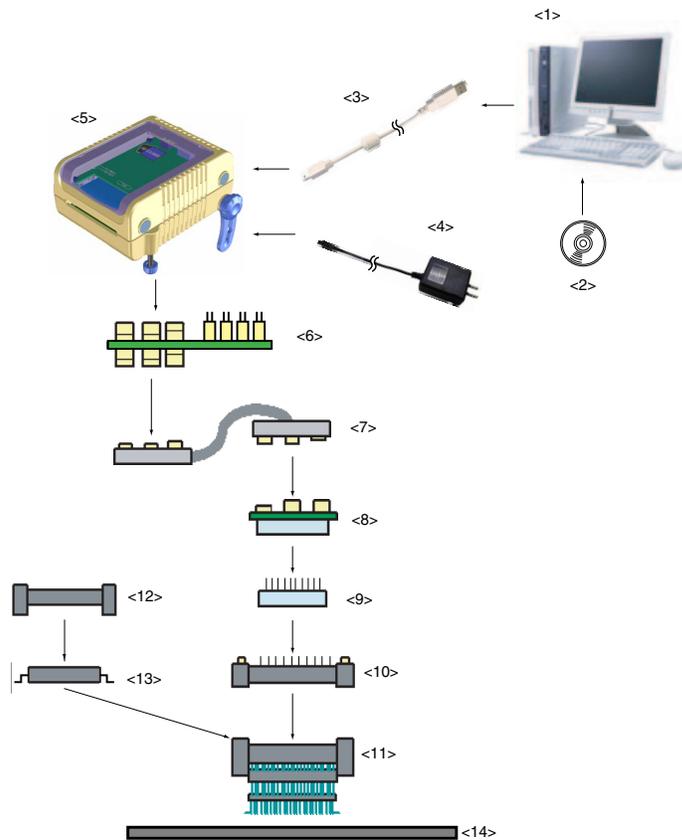
Parameter		Specification
Emulation memory capacity	Internal ROM	512 KB (MAX.)
	Internal RAM	61.75 KB (MAX.)
Program execution functions	Real-time execution function	Go, Start from Here, Come Here, Restart, Return Out, Ignore break points and Go
	Non-real-time execution function	Step In, Next Over, Slowmotion, Go & Go
Memory manipulation		Available (initialize, copy, compare)
Register manipulation		Available (general-purpose registers, control registers, SFRs)
Disassemble function		Available
Local variable view		Local variables
Watch data view		Local variables, global variables, or else
Stack trace view		Available
Break functions	Event break	Execution: 8 points Access: 8 points
	Software break	2000 points
	Pre-execution break	4 to 8 points <sup>Note</sup>
	Fail-safe break	Non-map, write protect, SFR illegal access, stack overflow, or else
	Other	Forcible break, trace full break, trace delay break, timeout break, timer overflow break
Trace functions	Trace data types	Program address, program data, access address, access data, status, time tag
	Trace modes	Unconditional trace, section trace, qualify trace, delay trigger trace
	Trace functions	Non-stop, full stop, full break, delay trigger stop, delay trigger break
	Memory capacity	128K frames
Real-time RAM monitoring function		All internal RAM spaces
Time measurement functions	Measurement clock	60 MHz
	Measurement objects	Start through end of program execution Start event through end event
	Maximum measurement time	Approx. 40 hours and 43 minutes (Resolution: 17 ns)
	Number of timers for measurement	Start through end of program execution: 1 Start event through end event: 2
	Measurement results	Execution time (start through end of execution) Maximum, minimum, average, total, pass count (between events)
	Other	Timer overflow break function, timeout break function
Other functions		Command functions set in the console, mapping function, event function, coverage function, snapshot function, DMM function, power-off emulation function, pin mask function, flash self programming emulation function

**Note** The number of breaks that can be set varies depending on the location where the break is set.

### 1.3 System Configuration

This section shows the system configuration when using the QB-78K0RKX3 connected to a PC (Windows PC (Windows2000 and WindowsXP), PC/AT™ compatible). Connection is possible even without optional products.

**Figure 1-1. System Configuration**



<1> Host machine	: Windows PC (Windows2000 and WindowsXP), IBM PC/AT compatible can be used
<2> ID78K0R-QB Disk/Accessory Disk	: Debugger, USB drivers, manual, etc.
<3> USB interface cable	: Cable connecting QB-78K0RKX3 to host machine
<4> AC adapter	: Support input AC100 to 240 V
<5> QB-78K0RKX3	: This product
<6> Check pin adapter (optional)	: Adapter used for monitoring waveforms with oscilloscope
<7> Emulation probe	: High-characteristic FPC type emulation probe
<8> Exchange adapter	: Adapter that performs pin conversion
<9> Space adapter (optional)	: Adapter used for height adjustment
<10> YQ connector	: Connector that connects exchange adapter to target connector
<11> Target connector	: Connector soldered to target system
<12> Mount adapter (optional)	: Adapter used for mounting target device into socket
<13> Device	: Target device
<14> Target system	

**Remarks 1.** Obtain device files from the NEC Electronics website.

<http://www.necel.com/micro/ods/eng/>

**2.** Refer to **1.5 Package Contents** for the purchase forms of the above products.

**3.** As for handling of connectors, refer to **2.5 Mounting and Connecting Connectors**.

## 1.4 System Configuration for Each Target Device

The following table lists the system configuration for each target device of the QB-78K0RKX3.

<R>

**Table 1-3. Adapters and Connectors for Each Target Device**

Target Device	Package	Exchange Adaptor	Space Adaptor	YQ Connector	Target Connector	Mount Adaptor
78K0R/KE3	64GB	QB-64GB-EA-08T	QB-64GB-YS-01T	QB-64GB-YQ-01T	QB-64GB-NQ-01T	QB-64GB-HQ-01T
	64GK	QB-64GK-EA-06T	QB-64GK-YS-01T	QB-64GK-YQ-01T	QB-64GB-NQ-01T	QB-64GK-HQ-01T
78K0R/KF3	80GC	QB-80GC-EA-06T	QB-80GC-YS-01T	QB-80GC-YQ-01T	QB-80GC-NQ-01T	QB-80GC-HQ-01T
	80GK	QB-80GK-EA-06T	QB-80GK-YS-01T	QB-80GK-YQ-01T	QB-80GK-NQ-01T	QB-80GK-HQ-01T
78K0R/KG3	100GC	QB-100GC-EA-01T	QB-100GC-YS-01T	QB-100GC-YQ-01T	QB-100GC-NQ-01T	QB-100GC-HQ-01T
	100GF	QB-100GF-EA-04T	QB-100GF-YS-01T	QB-100GF-YQ-01T	QB-100GF-NQ-01T	QB-100GF-HQ-03T
78K0R/KH3	128GF	QB-128GF-EA-01T	QB-128GF-YS-01T	QB-128GF-YQ-01T	QB-128GF-NQ-01T	QB-128GF-HQ-01T
78K0R/KJ3	144GJ	QB-144GJ-EA-05T	QB-144GJ-YS-01T	QB-144GJ-YQ-01T	QB-144GJ-NQ-01T	QB-144GJ-HQ-01T

<R>

**Table 1-4. Common Probe and Adapter**

Name	Part Number
Check pin adapter	QB-144-CA-01
Emulation probe	QB-144-EP-02S

<R>

The adapter and connector for each device, and common probe and adapter are sold separately. An exchange adapter, a YQ connector, a target connector, and an emulation probe are included, depending on the order product name. For details, refer to **1.5 Package Contents**.

**Remark** For the package drawings of the connector, adapter, and probe, refer to the following URL.  
<http://www.necel.com/micro/en/development/asia/Emulator/IE/iecube.html>

## 1.5 Package Contents

<R> The included products are described for each order product name.

### Products supplied with QB-78K0RKX3-ZZZ

- 1: QB-78K0RKX3
- 2: AC adapter
- 3: USB interface cable (2 meters)
- 4: Probe holder
- 5: Online user registration card (warranty card and software contract in one)
- 6: ID78K0R-QB Disk (CD-ROM)
- 7: Accessory Disk (CD-ROM)
- 8: IECUBE Setup Manual (Japanese/English)
- 9: Packing list
- 10: QB-MINI2

### Products supplied with QB-78K0RKX3-T144GJ

- 1 to 10
- 11: Emulation probe QB-144-EP-02S
  - 12: Exchange adapter QB-144GJ-EA-05T
  - 13: YQ connector QB-144GJ-YQ-01T
  - 14: Target connector QB-144GJ-NQ-01T

### Products supplied with QB-78K0RKX3-T128GF

- 1 to 10
- 11: Emulation probe QB-144-EP-02S
  - 12: Exchange adapter QB-128GF-EA-01T
  - 13: YQ connector QB-128GF-YQ-01T
  - 14: Target connector QB-128GF-NQ-01T

### Products supplied with QB-78K0RKX3-T100GC

- 1 to 10
- 11: Emulation probe QB-144-EP-02S
  - 12: Exchange adapter QB-100GC-EA-01T
  - 13: YQ connector QB-100GC-YQ-01T
  - 14: Target connector QB-100GC-NQ-01T

### Products supplied with QB-78K0RKX3-T100GF

- 1 to 10
- 11: Emulation probe QB-144-EP-02S
  - 12: Exchange adapter QB-100GF-EA-04T
  - 13: YQ connector QB-100GF-YQ-01T
  - 14: Target connector QB-100GF-NQ-01T

### Products supplied with QB-78K0RKX3-T80GC

- 1 to 10
- 11: Emulation probe QB-144-EP-02S
  - 12: Exchange adapter QB-80GC-EA-06T

- 13: YQ connector QB-80GC-YQ-01T
- 14: Target connector QB-80GC-NQ-01T

Products supplied with QB-78K0RKX3-T80GK

1 to 10

- 11: Emulation probe QB-144-EP-02S
- 12: Exchange adapter QB-80GK-EA-06T
- 13: YQ connector QB-80GK-YQ-01T
- 14: Target connector QB-80GK-NQ-01T

Products supplied with QB-78K0RKX3-T64GB

1 to 10

- 11: Emulation probe QB-144-EP-02S
- 12: Exchange adapter QB-64GB-EA-08T
- 13: YQ connector QB-64GB-YQ-01T
- 14: Target connector QB-64GB-NQ-01T

Products supplied with QB-78K0RKX3-T64GK

1 to 10

- 11: Emulation probe QB-144-EP-02S
- 12: Exchange adapter QB-64GK-EA-06T
- 13: YQ connector QB-64GK-YQ-01T
- 14: Target connector QB-64GK-NQ-01T

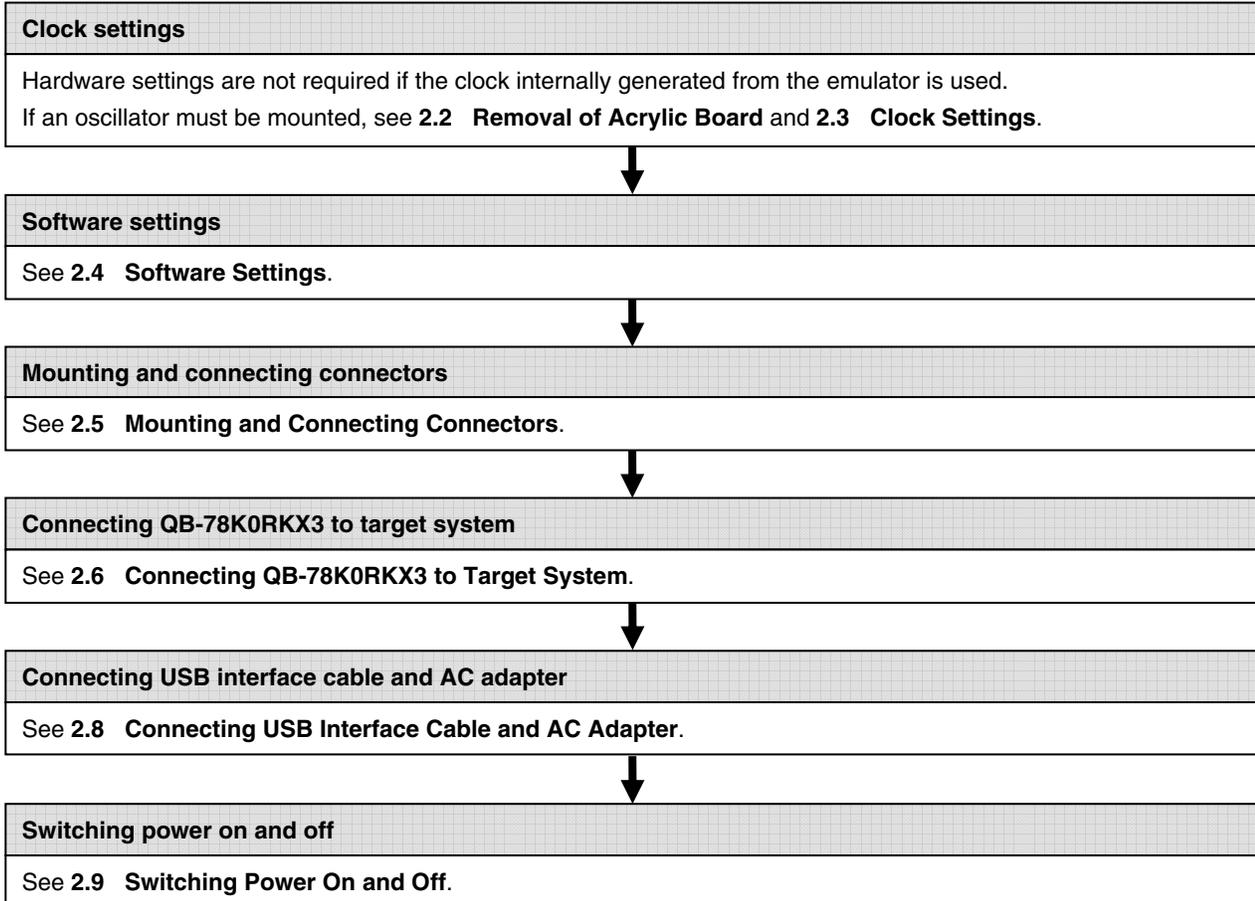
## CHAPTER 2 SETUP PROCEDURE

This chapter explains the QB-78K0RKX3 setup procedure.

Setup can be completed by performing installation setup in the order in which it appears in this chapter.

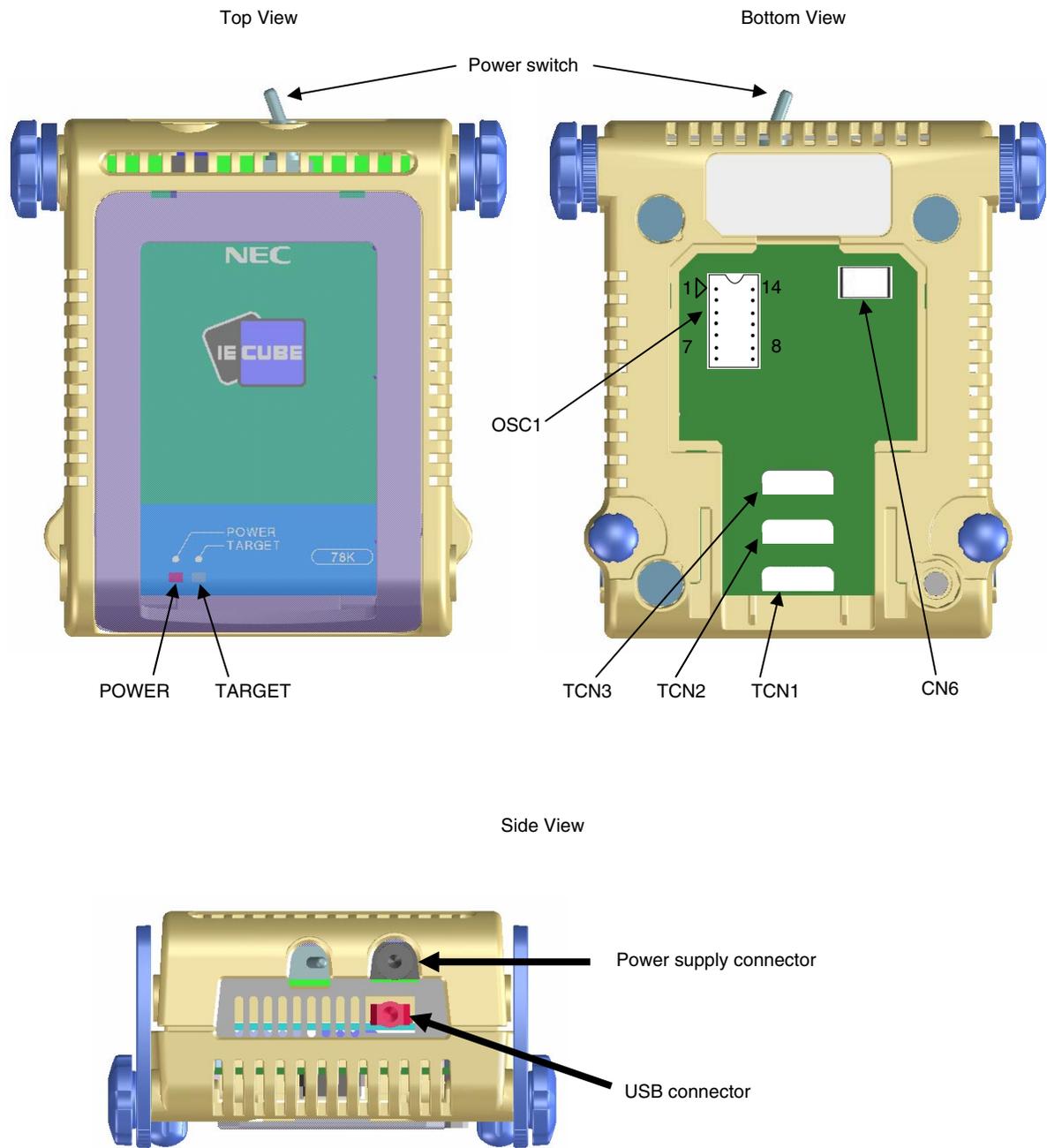
Perform setup along the lines of the following procedure.

See **2.1 Names and Functions of Hardware** for clock positions.



2.1 Names and Functions of Hardware

Figure 2-1. Names of Parts of QB-78K0RKX3



(1) TCN1, TCN2, TCN3

These are connectors for connecting a check pin adapter or emulation probe.

(2) OSC1

This is a socket for mounting the oscillator.

(3) CN6

This is a connector for the shipment inspection. It is not something that the user will need.

(4) POWER (Red LED)

This is an LED that shows whether the power supply of the QB-78K0RKX3 is switched on.

LED State	QB-78K0RKX3 State
Lit	Power switch ON
Not lit	Power switch OFF or AC adapter not connected to QB-78K0RKX3
Blinking	Internal error occurred (Contact an NEC Electronics sales representative or distributor)

(5) TARGET (Green LED)

This is an LED that shows whether the power supply of the target system is switched on.

LED State	Target System State
Lit	Target system power supply ON
Not lit	Target system power supply OFF or target system not connected

(6) Power switch

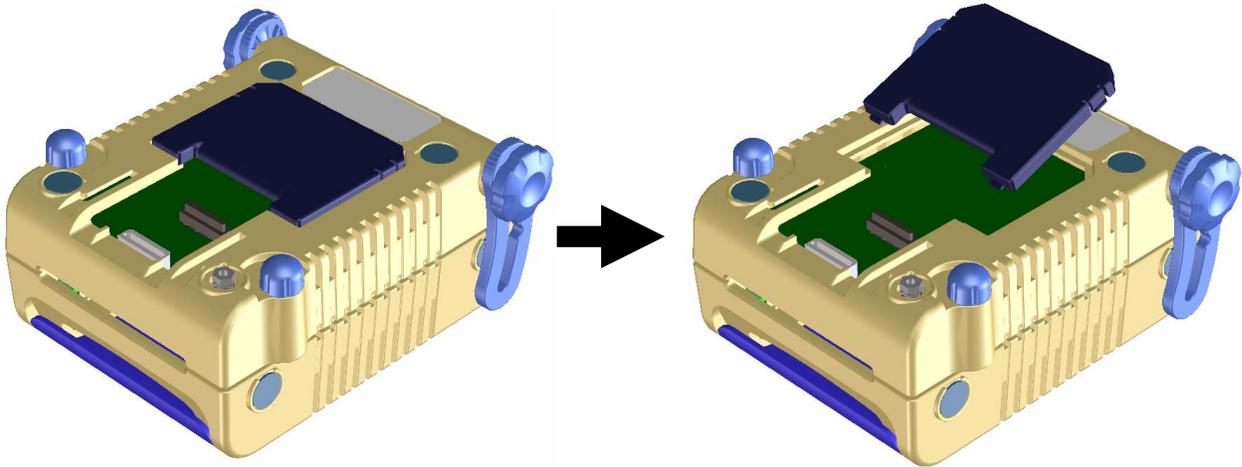
This is the power switch of the QB-78K0RKX3.

It is OFF at shipment.

## 2.2 Removal of Acrylic Board

To modify the clock setting, the acrylic board on the bottom of the QB-78K0RKX3 must be removed. The acrylic board can be removed by lifting it up.

**Figure 2-2. Acrylic Board Removal Method**



**<R> 2.3 Clock Settings****2.3.1 Overview of clock settings**

The following four types of clock settings are available.

Each clock setting is listed below.

Clock Used	Clock Supply	Debugger Setting (in Configuration Dialog)
(1) High-speed system clock <sup>Note 1</sup> (X1 oscillator or External input)	(a) When the clock generated within the emulator is used	System
	(b) When the clock is supplied from the target system	External
	(c) When the oscillator (OSC1) mounted onto the emulator is used	Clock Socket
(2) Internal high-speed oscillation clock	Uses the clock internally generated from the emulator	–
(3) Internal low-speed oscillation clock	Uses the clock internally generated from the emulator	–
(4) Subsystem clock <sup>Note 2</sup> (XT1 oscillator)	(a) When the clock generated within the emulator is used	System
	(b) When the clock is supplied from the target system	External

**Notes 1.** First, select “System” in the debugger settings (refer to (a) When the clock generated within the emulator is used, in (1) High-speed system clock).

If there is no clock that can be selected, follow the descriptions below.

- If the target system clock can supply a square wave for the emulator:

Select “External” in the debugger settings (refer to (b) When the clock is supplied from the target system, in (1) High-speed system clock).

- If the target system clock cannot supply a square wave for the emulator:

Mount onto the emulator the oscillator of the clock to be used and select “Clock Socket” in the debugger settings (refer to (c) When the oscillator (OSC1) mounted onto the emulator is used, in (1) High-speed system clock).

2. First, select “System” in the debugger settings (refer to (a) When the clock generated within the emulator is used, in (4) Subsystem clock).

If there is no clock that can be selected, it can be supplied from the target system clock. A square wave, however, must be supplied (refer to (b) When the clock is supplied from the target system, in (4) Subsystem clock).

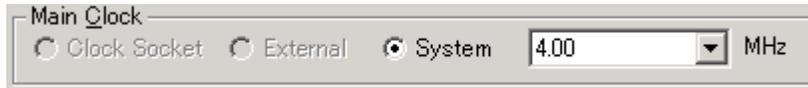
Oscillation with the resonator on the target system is not supported. Therefore, the in-circuit emulator cannot emulate the oscillation operation of the clock on the target system.

(1) High-speed system clock

The clock settings are listed below.

**Table 2-1. Settings for High-Speed System Clock**

Type of Clock to Be Used	OSC1	Debugger Setting
(a) When the clock generated within the emulator is used	–	System
(b) When the clock is supplied from the target system <sup>Note</sup>	–	External
(c) When the oscillator (OSC1) mounted onto the emulator is used	Oscillator mounted	Clock Socket



**Note** This setting is not possible when TARGET LED is not lit.

**Remarks 1.** Settings other than the above are prohibited.

**2.** Selection of (a) or (b) is possible regardless of whether the oscillator is not mounted in the OSC1 socket.

(a) When the clock generated within the emulator is used

Select the “System” in the debugger and select the desired frequency from the drop-down list.

The following frequencies are selectable.

2.00, 3.00, 3.57, 4.00, 4.19, 4.91, 5.00, 6.00, 8.00, 8.38, 10.00, 12.00, 16.00, 20.00 [MHz]

(b) When the clock is supplied from the target system

Select the “External” in the debugger. The clock input from the target system is then used.

Oscillation with the resonator on the target system is not supported. To input a clock from the target system, input to the clock pin (X2) the square-wave signal with the same voltage potential as that of the target device supply voltage (V<sub>DD</sub>). Inputting the inverted signal to X1 is not necessary.

The selectable frequencies are same as those of the target device.

(c) When the oscillator (OSC1) mounted onto the emulator is used

Mount an oscillator in the OSC1 socket in the emulator and then select the “Clock socket” in the debugger. The clock generated from the oscillator mounted on the emulator is used.

The selectable frequencies are same as those of the target device.

As an oscillator<sup>Note</sup> to be mounted in the OSC1 socket in the emulator, use the one that satisfies the following specifications.

- Supply voltage: 5 V
- Output level: CMOS

**Note** An oscillator that uses a resonator cannot be used.

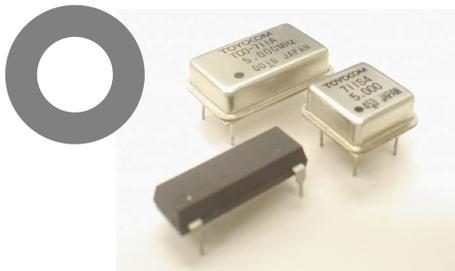


Figure 2-3. Oscillator Shape

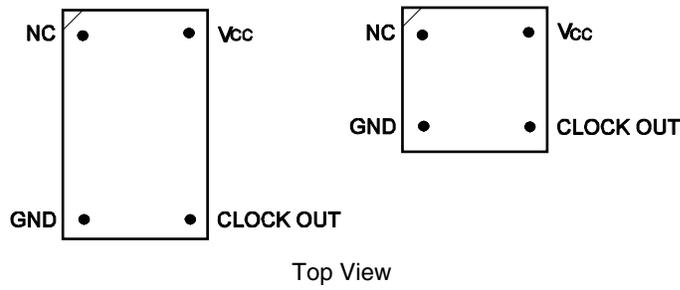
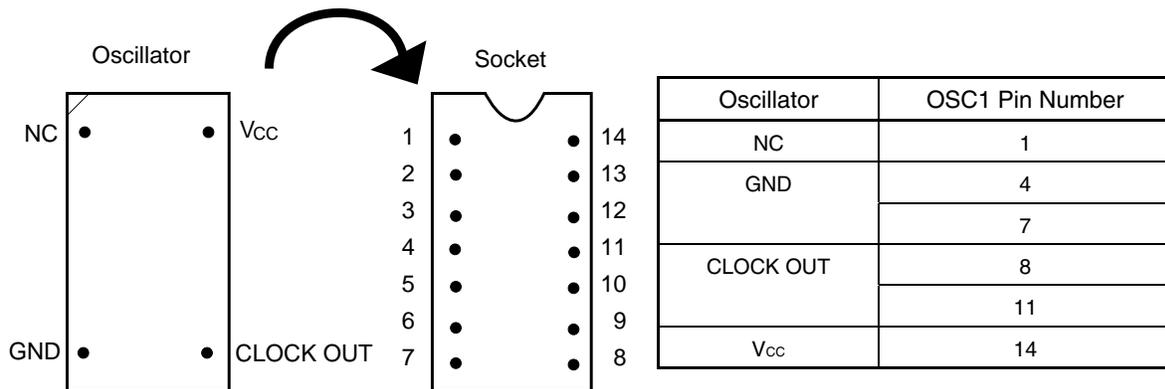


Figure 2-4. Mapping of Oscillator to Socket



**Remark** Insert the oscillator into the socket, take care for the pin 1 position.

(2) Internal high-speed oscillation clock

The debugger setting is not necessary.

The use of the internal high-speed oscillation clock can be specified in the user program.

(3) Internal low-speed oscillation clock

The debugger setting is not necessary.

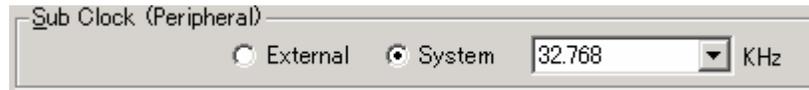
The use of the internal low-speed oscillation clock can be specified in the user program.

## (4) Subsystem clock

The clock settings are listed below.

**Table 2-2. Settings for Subsystem Clock**

Type of Clock to Be Used	Debugger Setting
(a) When the clock generated within the emulator is used	System
(b) When the clock is supplied from the target system <sup>Note</sup>	External



**Note** This setting is not possible when TARGET LED is not lit.

**Remark** Settings other than above are prohibited.

## (a) When the clock generated within the emulator is used

Select the “System” in the debugger and select “32.768” [kHz] as the frequency from the drop-down list.

32.768 [kHz]

**Remark** “38.400” [kHz] can also be selected from the list, but do not select this frequency; it is not supported by the device.

## (b) When the clock is supplied from the target system

Select the “External” in the debugger. The clock input from the target system is then used.

Oscillation with the resonator on the target system is not supported. To input a clock from the target system, input to the clock pin (XT2) the square-wave signal with the same voltage potential as that of the target device supply voltage ( $V_{DD}$ ). Inputting the inverted signal to XT1 is not necessary.

The selectable frequencies are same as those of the target device.

## 2.4 Software Settings

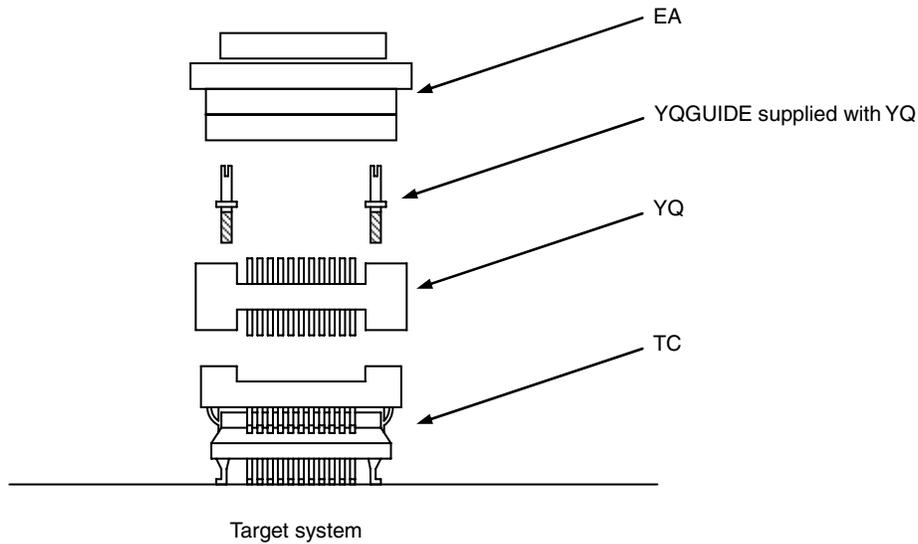
For details, see the **ID78K0R-QB Ver. 3.20 Integrated Debugger Operation User's Manual** (U17839E).



&lt;R&gt;

**2.5.2 Mounting YQ to TC**

- (1) After confirming that there are no broken or bent YQ contact pins, fit the YQ in the TC and fasten it using the supplied YQGUIDE (for the fastening method, see the next step, (2)). If repeatedly inserting and removing, be sure to inspect the YQ pins before fitting. If pins are bent, correct them using something thin and flat such as the edge of a knife.
  
- (2) Fasten YQ to the TC on the target system using the supplied YQGUIDE. Fasten the screws equally in the four corners using the supplied flat-blade screwdriver or a torque driver. The tightening torque of the YQGUIDE is 0.054 Nm (MAX.). Too great tightening causes bad connections.  
However, four screws for fitting to the TC (M2 x 10 mm / 4 units) are included with the YQ.



### 2.5.3 Plugging EA into YQ

Match the pin 1 position of the YQ or SA (corner cuts match in both) to the pin 1 position of the EA and plug in.

- When plugging or unplugging, press on the TC, YQ, and SA with a finger so that there is no force on the TC.
- When plugging or unplugging, be careful of the direction of wiggling.

As a tool when unplugging, insert some kind of thin non-conductive material such as a wooden stick between the YQ (SA) and EA and wiggle while slowly unplugging. Be careful since the connector will be damaged if this is done in the wrong direction.

### 2.5.4 Precautions for handling TC, YQ, SA, and CA

- (1) When taking the TC from the box, press down on the body and take out the sponge first.
- (2) Since the pins of the YQ are thin and easily bent, be careful. When inserting it in the TC, confirm that there are no bent pins.
- (3) When screwing a YQ soldered to a board to the TC, fasten the screws in four places in turn using a #0 or #1 Phillips precision screwdriver or torque driver after tentatively tightening them. Fix the torque at 0.054 Nm (MAX.).  
If just one place is overtightened, it may cause poor contact. Moreover, a board being connected to the YQ must have accessory holes in prescribed positions (four places:  $\phi 2.3$  mm or  $\phi 3.3$  mm). The  $\phi 3.8$  mm or  $\phi 4.3$  mm that is the screw head size is an area where wiring is prohibited.
- (4) In YQ and SA removal, since there is a danger of YQ pins being bent or broken when prying and wiggling, remove them gradually using a flatbladed screwdriver from four directions. Moreover, to connect and use the YQ and SA, screw the YQ to the TC according to the YQGUIDE (included with the YQ) using a 2.3 mm flatbladed screwdriver and then connect it to the SA. Fix the torque at 0.054 Nm (MAX.). If even one place is overtightened, it may cause poor contact.
- (5) For the TC, YQ, and SA, since there is a danger that washing fluid on the structure will remain in the connector, do not perform washing.
- (6) TC, IC, and YQ cannot be used in combination.
- (7) A TC/YQ system cannot be used in an environment of vibrations or shocks.
- (8) It is assumed that this product will be used in system development and evaluation. Moreover, when used in Japan, Electrical Appliance and Material Control Law and electromagnetic disturbance countermeasures have not been applied.
- (9) Since there are rare cases of shape change if the box is left for a long time in a place where it is 50°C or higher, for safekeeping, store it in a place where it is no higher than 40°C and direct sunlight does not hit it.
- (10) For details about handling the TC, YQ, and SA, see the NQPACK series technical materials at the website of Tokyo Eletech Corporation.

URL: <http://www.tetc.co.jp/>

#### (11) CA

The CA is an optional product for IECUBE, and can be used to measure the waveform between IECUBE and the target system.

Since the pins on the CA do not correspond to the pin layout in each device, the pin header cover must be mounted according to the device to be used. For mounting methods of the pin header cover, refer to

**[Related Information]** on the following URL.

<http://www.necel.com/micro/english/iecube/index.html>

**2.5.5 Precautions for mounting IC using TC and MA**

- (1) Confirm that there is no weld flash in the resin (sealant part) of the IC. If there is weld flash, remove it using a knife or the like.
- (2) Confirm that there is no weld flash breaking or bending of IC leads. In particular, confirm the planarity of IC leads. If there is abnormality in the planarity, correct that portion.
- (3) Viewing the TC contact pins from the top, if there are foreign bodies on them, remove them using a brush or the like.  
After confirming (1) to (3), fit the IC to the TC. Also fit the MA.
- (4) Put the supplied M2 x 6 mm screws in the four accessory holes of the MA and fasten the screws in opposite corners. At that time, use either the dedicated screwdriver that is supplied or a torque driver to fasten them equally in turn with a tightening torque of 0.054 Nm (MAX.). Since the contact is poor if tightening is too great, once you have lightly fastened the MA screws, tighten them again.
- (5) Depending on the use environment, when starting up a device that has been left for a long time, starting it may be difficult. In this case, loosen the screws slightly and then retighten them.
- (6) If startup still is difficult after (5) above, check (1) to (3) again.
- (7) Tightening the screws of the MA too much may give rise to cracks in the molded part of the MA (plastic part) and bend the mold into a bowed shape, making contact poor.
- (8) After soldering the TC, do not perform cleaning by flux immersion or vapor.

## 2.6 Connecting QB-78K0RKX3 to Target System

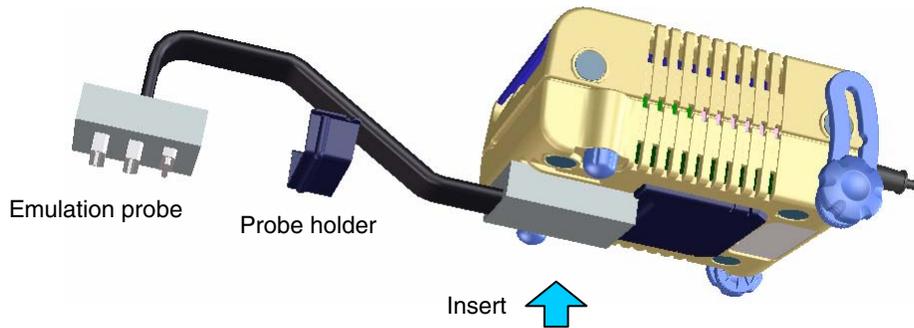
If connecting the emulation probe (QB-144-EP-02S), connect it to the QB-78K0RKX3 and the target system by the following procedure.

### (a) Connecting probe holder

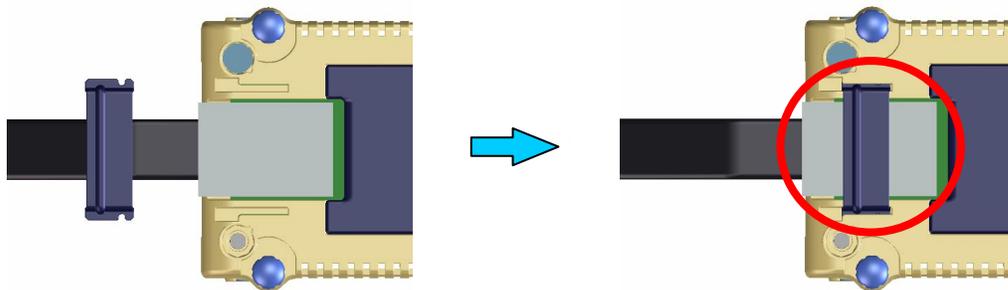
Use the probe holder (supplied with the QB-78K0RKX3) to connect the emulation probe to the QB-78K0RKX3, as shown below.

**Figure 2-5. Using Probe Holder**

<1> Connect the QB-78K0RKX3 to the probe.



<2> Insert the probe holder into QB-78K0RKX3



Insert the probe holder into the QB-78K0RKX3 until you hear a click (note the direction).

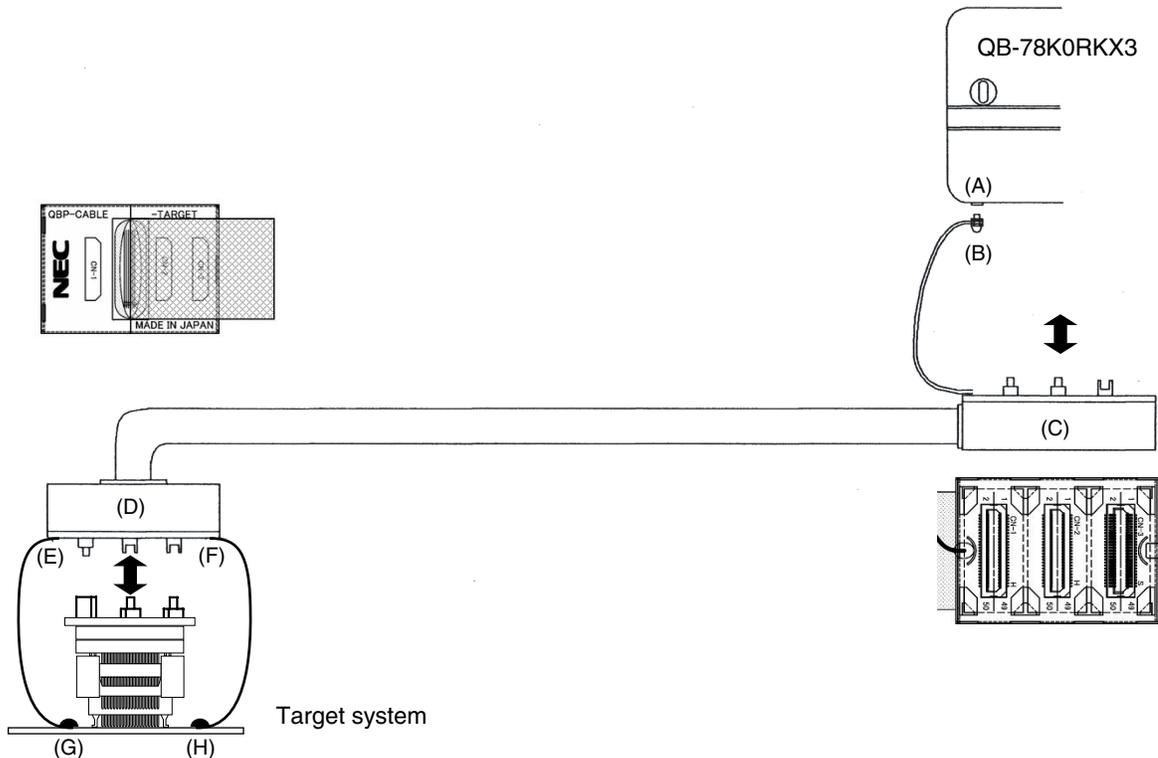
### (b) Connection of emulation probe GND wire

There are three GND wires in the emulation probe. Connect them to the QB-78K0RKX3 and target system.

<1> Fasten the GND wire on the QB-78K0RKX3 side of the emulation probe to the nut on the bottom of the QB-78K0RKX3 using a #0 or #1 Phillips precision screwdriver (connection of B to A in **Figure 2-6**).

<2> Next insert the connector on the top of the emulation probe into the connector at the opening on the bottom of the QB-78K0RKX3 from below being careful of the insertion direction (connection of C in **Figure 2-6** to QB-78K0RKX3).

Figure 2-6. GND Wire



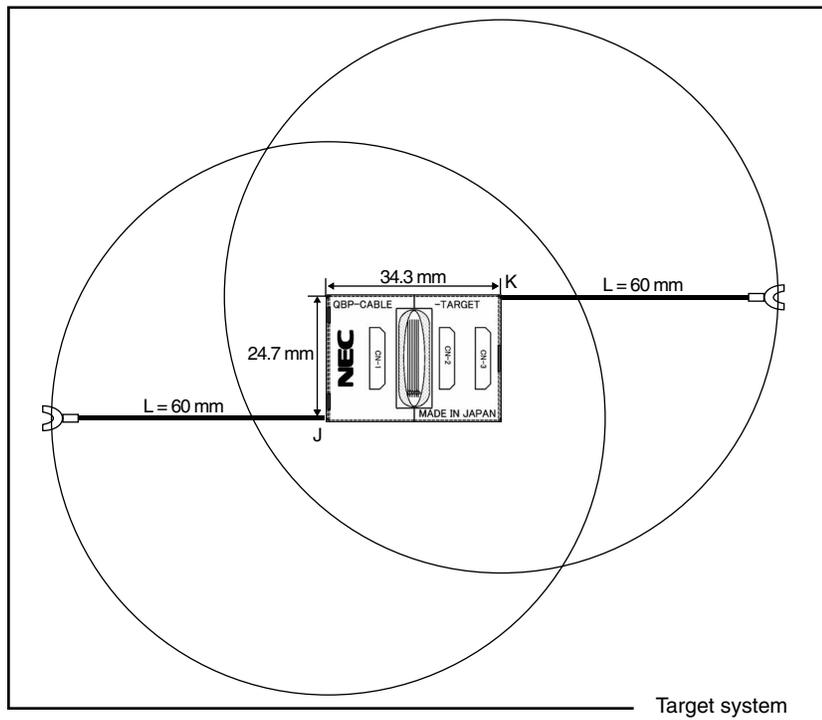
<3> Connect the exchange adapter and emulation probe to the target connector.

<4> Connect the two GND wires on the target system side of the emulation probe to the target system GND. If a pin or screw is fastened to the target system GND, remove the transparent terminal cover on the end of the GND wire and fasten the Y terminal of the GND wire to the target system (G in **Figure 2-6**). If the GND on the target system is an exposed pad, likewise fasten the Y terminal to the pad on the target system by soldering (H in **Figure 2-6**) (recommended soldering iron temperature setting: 300°C).

<5> If the target system has only one GND, connect only one of the GND wires of the emulation probe. Cut off the other GND wires with a nipper or leave it as is without removing the pin cover.

<6> Since the length of the GND wire below the head (insulated part) is approximately 60 mm, there must be at least a GND to which it can be connected to within the range of the two approximately 60 mm radius sections of the target system for connecting the emulation probe, as shown in **Figure 2-7**. The GND wire of the emulation probe is soldered to positions J and K in **Figure 2-7**.

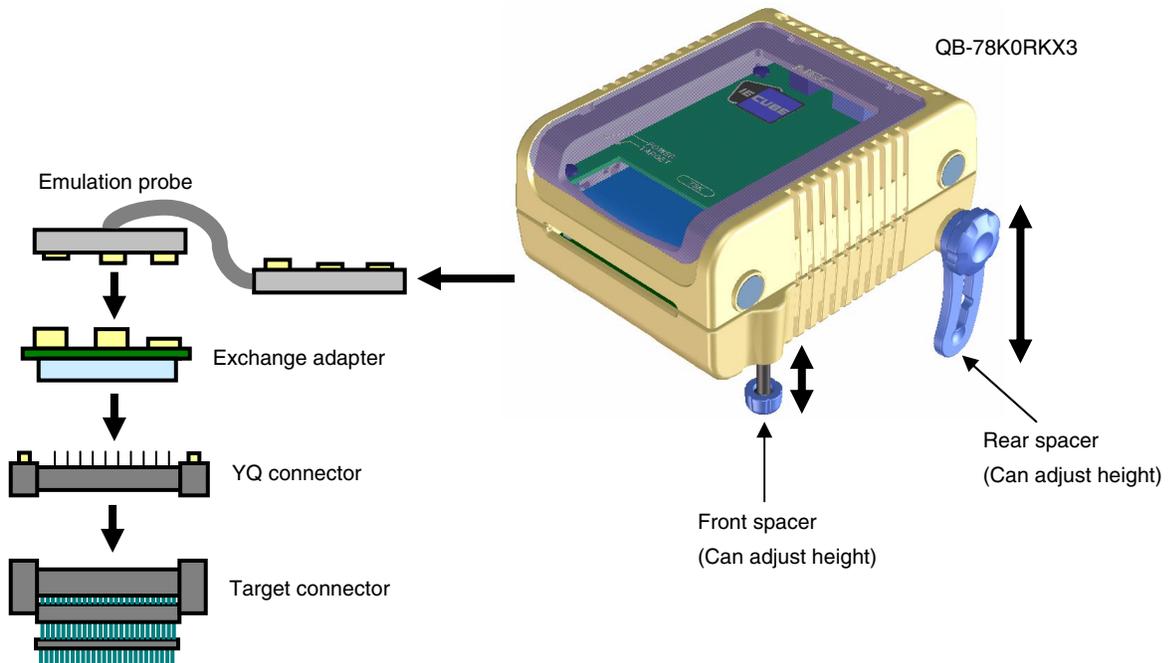
Figure 2-7. Where GND Wire Can Be Connected



(c) Ensuring isolation

When connecting the target system to the QB-78K0RKX3 using an emulation probe, perform height regulation using the front spacer or rear spacer of the QB-78K0RKX3 and ensure isolation from the target system.

Figure 2-8. Connection Using Emulation Probe



## (d) Precautions related to emulation probe

- <1> Be careful that stress of the emulation probe is not placed on the target connector. Moreover, when removing the emulation probe, remove it slowly while pressing down on the exchange adapter with a finger so that there is no stress on the target connector.
- <2> Be sure to connect the GND wire of the emulation probe to the QB-78K0RKX3 and the target system. If it cannot be connected, the impedance of the cable is unstable and could bring about lowering of signal transmission characteristics or distortion of the output waveform for an input waveform.

## 2.7 Notes on Power Supply and GND Pin Connection

For power supplies and GND pins of the target device, be sure to connect all pins to each power supply or GND.

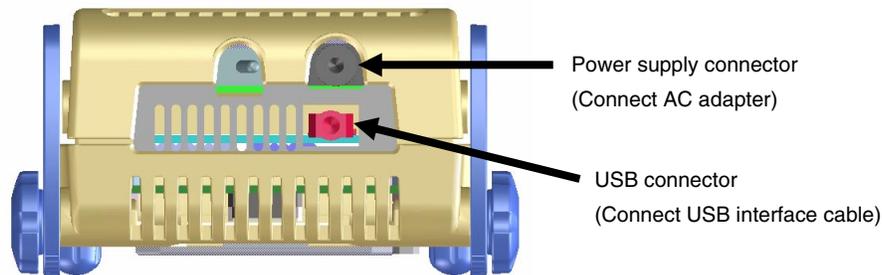
## 2.8 Connecting USB Interface Cable and AC Adapter

Plug the USB interface cable supplied with the QB-78K0RKX3 into the USB connector of the host machine, and plug the other side into the USB connector on the rear of the QB-78K0RKX3.

Plug the AC adapter supplied with the QB-78K0RKX3 into a receptacle and plug the other side into the power supply connector on the rear of the QB-78K0RKX3.

For QB-78K0RKX3 connector positions, see **Figure 2-9**.

**Figure 2-9. Connector Positions**



## 2.9 Switching Power On and Off

Be sure to switch the power on and off according to the following procedures.

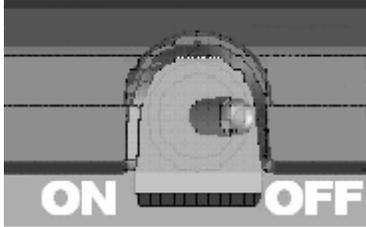
- |  |   |
|--|---|
| - Switching power on                       | - Switching power off                       |
| <1> QB-78K0RKX3 power on                   | <1> Debugger termination                    |
| <2> Target system power on <sup>Note</sup> | <2> Target system power off <sup>Note</sup> |
| <3> Debugger startup                       | <3> QB-78K0RKX3 power off                   |

**Note** In the procedures, <2> is unnecessary if the target system is not connected.

**Caution** If the wrong sequence was used for the operation, the target system or QB-78K0RKX3 may fail

## CHAPTER 3 SETTINGS AT PRODUCT SHIPMENT

Table 3-1. Settings at Shipment

Item	Setting	Remarks
OSC1	Not mounted	Oscillator can be mounted <sup>Note</sup> .
Power switch		Set to OFF at shipment.

**Note** The oscillation circuit using an oscillation cannot be used.

## CHAPTER 4 CAUTIONS

- Target system voltage during a break  
Do not decrease the voltage of the target system during a break.  
A reset that is generated by the low-voltage detector (LVI) or by power-on-clear (POC) during a break may cause an incorrect operation of the debugger or communication errors.
- Flash self programming emulation  
<1> Deleting and writing will operate normally even if initialize function “FlashEnv” is used to set the CPU frequency to a setting different from the actual operating frequency.  
<2> Writing can be performed normally even for an area that has not been deleted.
- Port pull-up resistor option register  
The time until a pull-up resistor becomes valid after it has been set so by using the port pull-up resistor option register (PUx) differs from the device.  
Device: Valid after 2 clocks, after setting  
QB-78K0RKX3: Valid after about 150 ns, after setting
- Input port functions  
The input port characteristics of P62 and P63 differ from the device.

**Table 4-1. The input port characteristics of P62 and P63**

Parameter		Conditions	MIN.	MAX.	Unit
Device	High level input voltage (V <sub>IH</sub> )	1.8 V ≤ V <sub>DD</sub> < 5.5 V	0.7 V <sub>DD</sub>	6.0	V
	Low level input voltage (V <sub>IL</sub> )	1.8 V ≤ V <sub>DD</sub> < 5.5 V	0	0.3 V <sub>DD</sub>	V
QB-78K0RKX3	High level input voltage (V <sub>IH</sub> )	2.7 V ≤ V <sub>DD</sub> ≤ 5.5 V	0.8 V <sub>DD</sub>	5.5	V
		1.8 V ≤ V <sub>DD</sub> < 2.7 V	0.85 V <sub>DD</sub>	5.5	V
	Low level input voltage (V <sub>IL</sub> )	2.7 V ≤ V <sub>DD</sub> ≤ 5.5 V	0	0.3 V <sub>DD</sub>	V
		1.8 V ≤ V <sub>DD</sub> < 2.7 V	0	0.2 V <sub>DD</sub>	V

**Remark** Device : CMOS input  
QB-78K0RKX3 : Schmitt input

- ANI pin characteristics  
If a series resistor has been inserted into the ANI pin, the voltage drop becomes larger and the A/D conversion value becomes lower than the device.  
**Example:** If a 10 kΩ series resistor has been connected to the ANI pin and 5.5 V have been input, the voltage drops to 5.3 V.
- D/A converter function  
The time required to perform D/A conversion by using the D/A converter function differs from the device.  
Device:                   Maximum conversion time during 1.8 V ≤ V<sub>DD</sub> < 2.7 V operation: 3 μs  
                              Maximum conversion time during 2.7 V ≤ V<sub>DD</sub> ≤ 5.5 V operation: 6 μs  
QB-78K0RKX3:       Average conversion time during 1.8 V ≤ V<sub>DD</sub> ≤ 5.5 V operation: 6 μs

○ Internal high-speed oscillator trimming register (HIOTRM)

Emulating the internal high-speed oscillator trimming register (HIOTRM) is not supported.

The internal high-speed oscillator operates at 8 MHz ( $\pm 1\%$ ), regardless of the setting of HIOTRM.

○ Device restrictions

With respect to the device restrictions, the operation of the emulator differs from that of the device, because the following items do not correspond to all control symbols with the QB-78K0RKX3.

See **Internal high-speed oscillator trimming register (HIOTRM)**, above, for the internal high-speed oscillator trimming register (HIOTRM).

- Restriction related to temperature correction of the 8 MHz internal high-speed oscillator
- Restriction related to low-voltage operation of the A/D converter
- Restriction imposed due to a conflict of instructions associated with DMA transfer operations and RAM value read operations

## APPENDIX A CHARACTERISTICS OF TARGET INTERFACE

The target interface (signals connecting the in-circuit emulator and target system) operate, in terms of function, as if an actual device were connected. The characteristics, however, may be different from those of the actual device.

The target interface of this product is one of the following shown in **Figure A-1**. **Table A-1** shows the processing of each target interface.

**Figure A-1. Equivalent Circuit of Target Interface (1/6)**

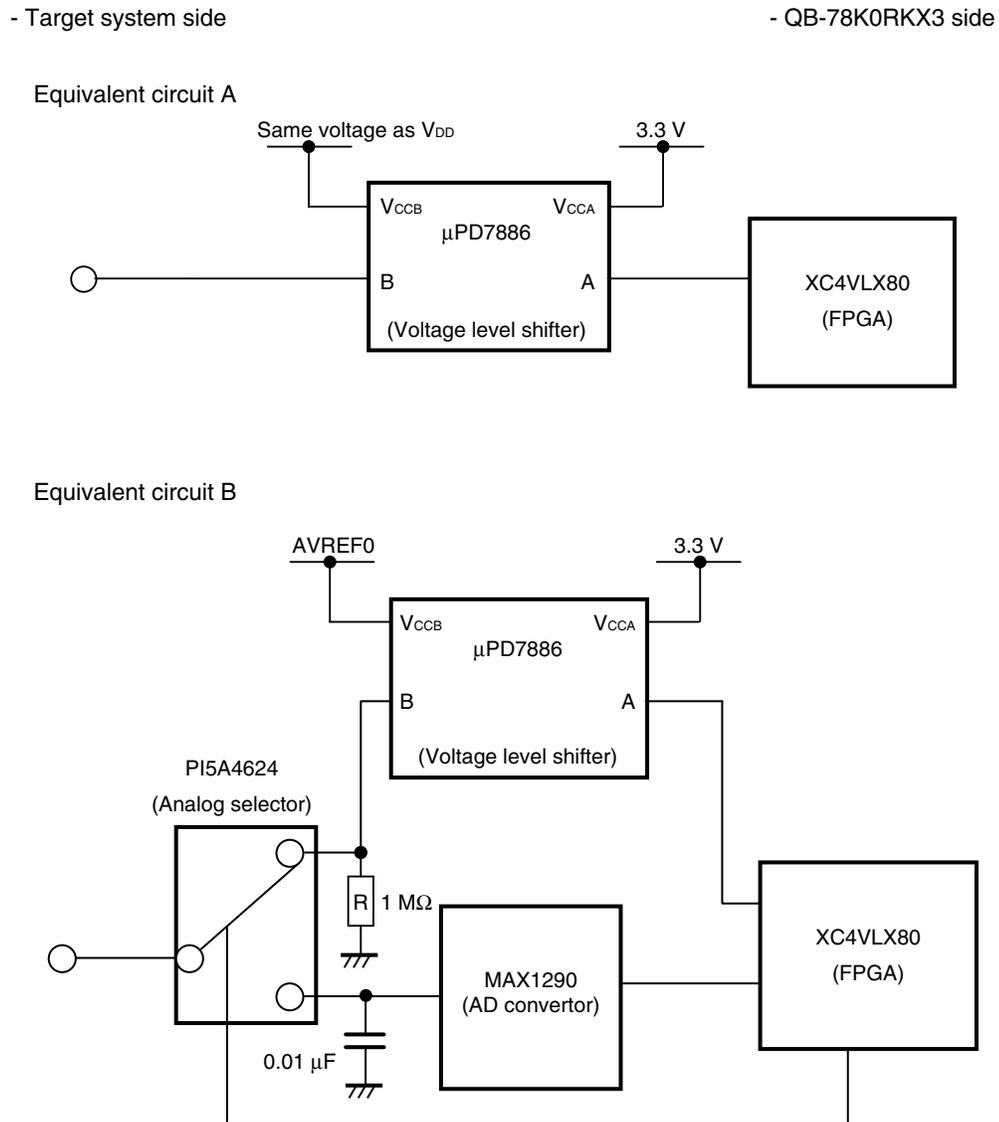
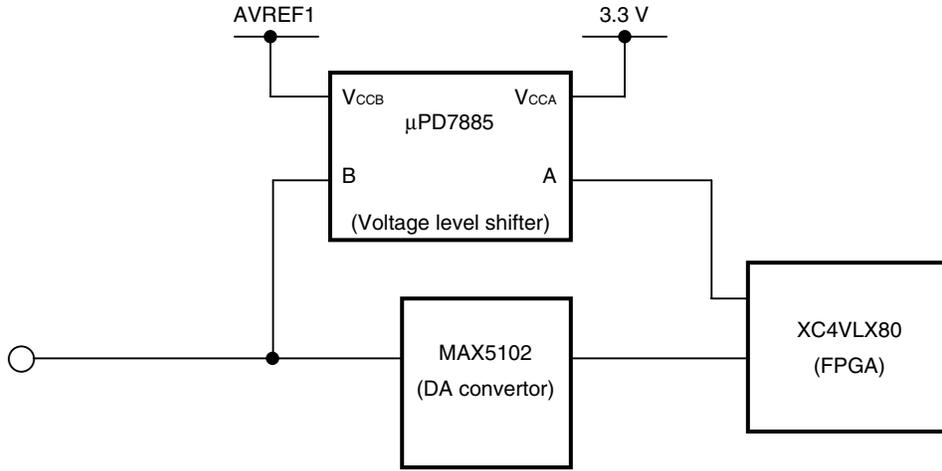


Figure A-1. Equivalent Circuit of Target Interface (2/6)

- Target system side

- QB-78K0RKX3 side

Equivalent circuit C



Equivalent circuit D

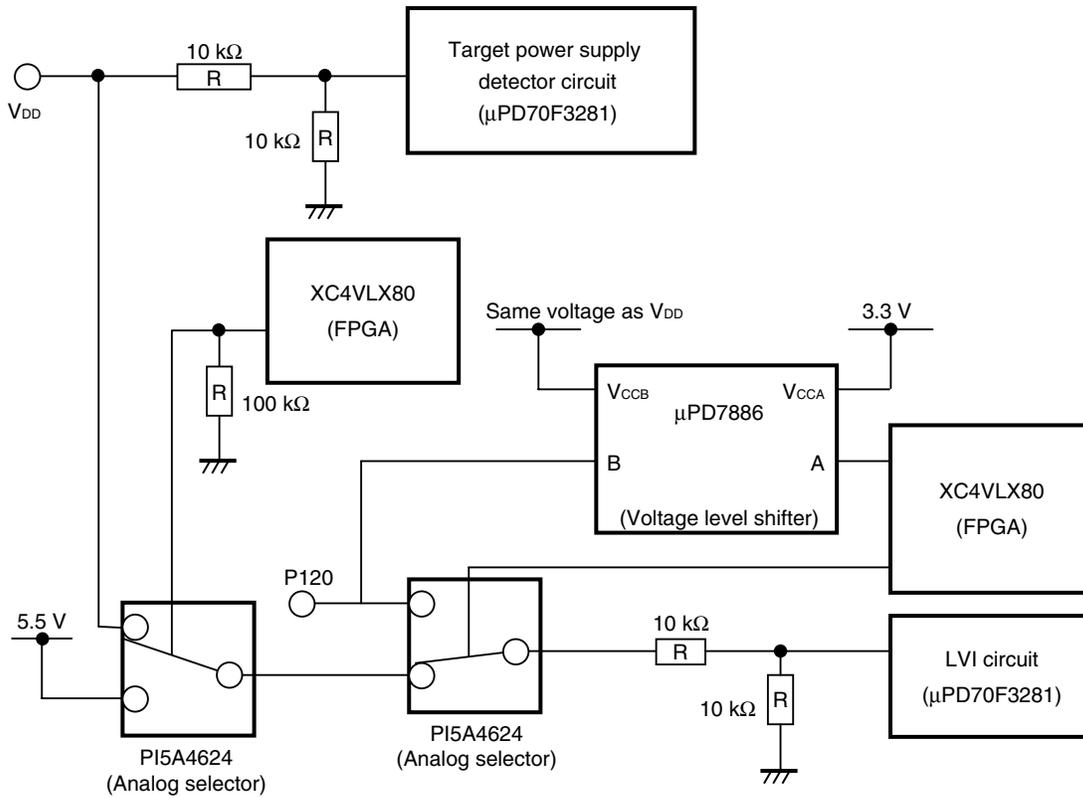
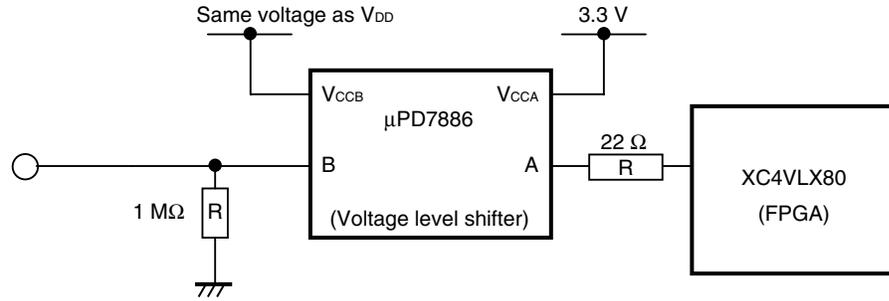


Figure A-1. Equivalent Circuit of Target Interface (3/6)

- Target system side

- QB-78K0RKX3 side

Equivalent circuit E



Equivalent circuit F

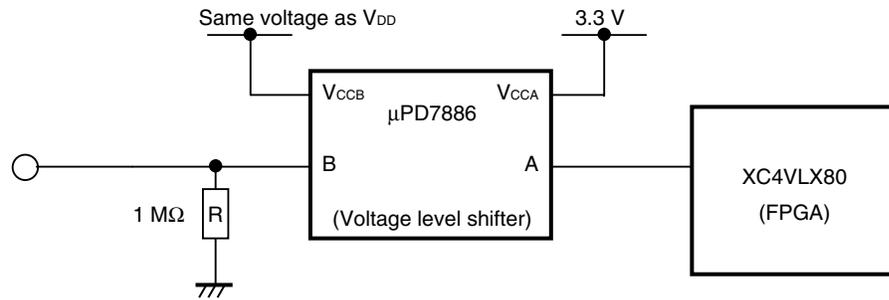
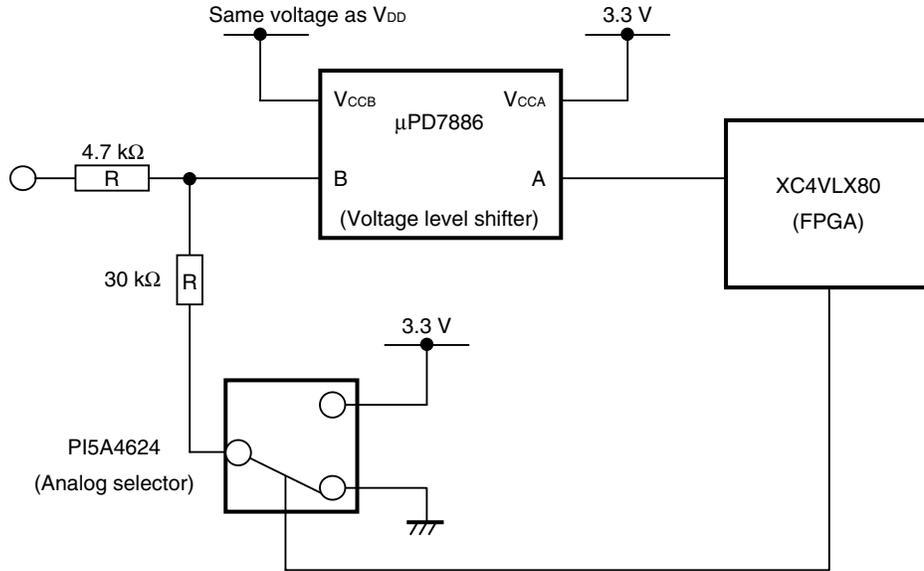


Figure A-1. Equivalent Circuit of Target Interface (4/6)

- Target system side

- QB-78K0RKX3 side

Equivalent circuit G



Equivalent circuit H

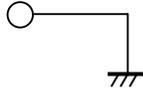


Figure A-1. Equivalent Circuit of Target Interface (5/6)

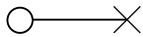
- Target system side

- QB-78K0RKX3 side

Equivalent circuit I



Equivalent circuit J



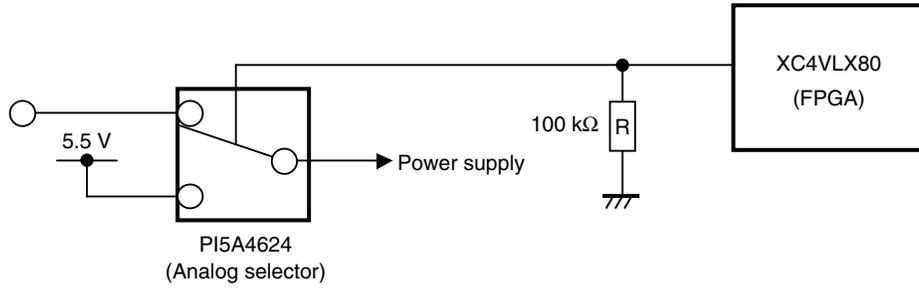
Open

Figure A-1. Equivalent Circuit of Target Interface (6/6)

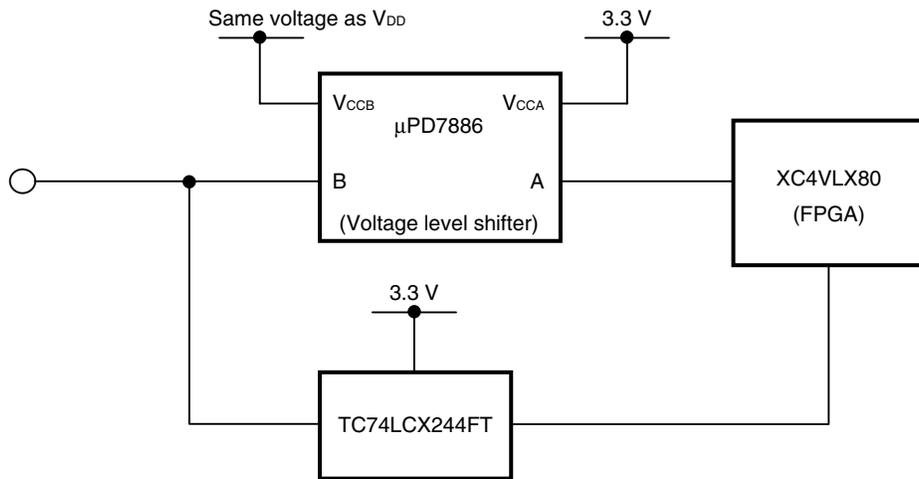
- Target system side

- QB-78K0RKX3 side

Equivalent circuit K



Equivalent circuit L



**Table A-1. Target Interface Combinations (1/14)**

KE3 (64GB/64GK) Pin Number	Pin Name in Target Device (78K0R/KX3)	Equivalent Circuit
1	P120/INTP0/EXLVI	D
2	P43/SCK01	L
3	P42/TI04/TO04	A
4	P41/TOOL1	A
5	P40/TOOL0	A
6	RESET	F
7	P124/XT2/EXCLKS	E
8	P123/XT1	A
9	FLMD0	G
10	P122/X2/EXCLK	E
11	P121/X1	A
12	REGC	J
13	V <sub>SS</sub>	H
14	EV <sub>SS</sub>	I
15	V <sub>DD</sub>	D
16	EV <sub>DD</sub>	D
17	P60/SCL0	A
18	P61/SDA0	A
19	P62	A
20	P63	A
21	P31/TI03/TO03/INTP4	A
22	P77/KR7/INTP11	A
23	P76/KR6/INTP10	A
24	P75/KR5/INTP9	A
25	P74/KR4/INTP8	A
26	P73/KR3	A
27	P72/KR2	A
28	P71/KR1	A
29	P70/KR0	A
30	P06/TI06/TO06	A
31	P05/TI05/TO05	A
32	P30/INTP3/RTC1HZ	A

Table A-1. Target Interface Combinations (2/14)

KE3 (64GB/64GK) Pin Number	Pin Name in Target Device (78K0R/KX3)	Equivalent Circuit
33	P50/INTP1	A
34	P51/INTP2	A
35	P52	A
36	P53	A
37	P54	A
38	P55	A
39	P17/TI02/TO02	A
40	P16/TI01/TO01/INTP5	A
41	P15/RTCDIV/RTCCL	A
42	P14/RXD3	A
43	P13/TXD3	A
44	P12/SO00/TXD0	A
45	P11/SI00/RXD0	A
46	P10/ $\overline{\text{SCK00}}$	A
47	AV <sub>REF0</sub>	K
48	AV <sub>SS</sub>	I
49	P27/ANI7	B
50	P26/ANI6	B
51	P25/ANI5	B
52	P24/ANI4	B
53	P23/ANI3	B
54	P22/ANI2	B
55	P21/ANI1	B
56	P20/ANI0	B
57	P130	A
58	P04/ $\overline{\text{SCK10}}$ /SCL10	L
59	P03/SI10/RXD1/SDA10	L
60	P02/SO10/TXD1	A
61	P01/TO00	A
62	P00/TI00	A
63	P141/PCLBUZ1/INTP7	A
64	P140/PCLBUZ0/INTP6	A

**Table A-1. Target Interface Combinations (3/14)**

KF3 (80GC/80GK) Pin Number	Pin Name in Target Device (78K0R/KX3)	Equivalent Circuit
1	P120/INTP0/EXLVI	D
2	P47	A
3	P46	A
4	P45/SO01	A
5	P44/SI01	L
6	P43/SCK01	L
7	P42/TI04/TO04	A
8	P41/TOOL1	A
9	P40/TOOL0	A
10	RESET	F
11	P124/XT2/EXCLKS	E
12	P123/XT1	A
13	FLMD0	G
14	P122/X2/EXCLK	E
15	P121/X1	A
16	REGC	J
17	V <sub>SS</sub>	H
18	EV <sub>SS</sub>	I
19	V <sub>DD</sub>	D
20	EV <sub>DD</sub>	D
21	P60/SCL0	A
22	P61/SDA0	A
23	P62	A
24	P63	A
25	P31/TI03/TO03/INTP4	A
26	P64	A
27	P65	A
28	P66	A
29	P67	A
30	P77/KR7/INTP11	A
31	P76/KR6/INTP10	A
32	P75/KR5/INTP9	A
33	P74/KR4/INTP8	A
34	P73/KR3	A
35	P72/KR2	A
36	P71/KR1	A
37	P70/KR0	A
38	P06/TI06/TO06	A
39	P05/TI05/TO05	A
40	P30/INTP3/RTC1HZ	A

Table A-1. Target Interface Combinations (4/14)

KF3 (80GC/80GK) Pin Number	Pin Name in Target Device (78K0R/KX3)	Equivalent Circuit
41	P50/INTP1	A
42	P51/INTP2	A
43	P52	A
44	P53	A
45	P54	A
46	P55	A
47	P17/TI02/TO02	A
48	P16/TI01/TO01/INTP5	A
49	P15/RTCDIV/RTCCL	A
50	P14/RXD3	A
51	P13/TXD3	A
52	P12/SO00/TXD0	A
53	P11/SI00/RXD0	A
54	P10/SCK00	A
56	AV <sub>REF1</sub>	K
57	P110/ANO0	C
58	P111/ANO1	C
59	AV <sub>REF0</sub>	K
60	AV <sub>SS</sub>	I
61	P27/ANI7	B
62	P26/ANI6	B
63	P25/ANI5	B
64	P24/ANI4	B
65	P23/ANI3	B
66	P22/ANI2	B
67	P21/ANI1	B
68	P20/ANI0	B
69	P130	A
70	P04/SCK10/SCL10	L
71	P03/SI10/RXD1/SDA10	L
72	P02/SO10/TXD1	A
73	P01/TO00	A
74	P00/TI00	A
75	P145/TI07/TO07	A
76	P144/SO20/TXD2	A
77	P143/SI20/RXD2/SDA20	L
78	P142/SCK20/SCL20	L
79	P141/PCLBUZ1/INTP7	A
80	P140/PCLBUZ0/INTP6	A

Table A-1. Target Interface Combinations (5/14)

KG3 (100GC) Pin Number	Pin Name in Target Device (78K0R/KX3)	Equivalent Circuit
1	P142/SCK20/SCL20	L
2	P141/PCLBUZ1/INTP7	A
3	P140/PCLBUZ0/INTP6	A
4	P120/INTP0/EXLVI	D
5	P47/INTP2	A
6	P46/INTP1/TI05/TO05	A
7	P45/SO01	A
8	P44/SI01	L
9	P43/SCK01	L
10	P42/TI04/TO04	A
11	P41/TOOL1	A
12	P40/TOOL0	A
13	RESET	F
14	P124/XT2/EXCLKS	E
15	P123/XT1	A
16	FLMD0	G
17	P122/X2/EXCLK	E
18	P121/X1	A
19	REGC	J
20	V <sub>SS</sub>	H
21	EV <sub>SS</sub>	I
22	V <sub>DD</sub>	D
23	EV <sub>DD</sub>	D
24	P60/SCL0	A
25	P61/SDA0	A
26	P62	A
27	P63	A
28	P31/TI03/TO03/INTP4	A
29	P64/RD	A
30	P65/WR0	A
31	P66/WR1	A
32	P67/ASTB	A
33	P77/EX23/KR7/INTP11	A
34	P76/EX22/KR6/INTP10	A
35	P75/EX21/KR5/INTP9	A
36	P74/EX20/KR4/INTP8	A
37	P73/EX19/KR3	A
38	P72/EX18/KR2	A
39	P71/EX17/KR1	A
40	P70/EX16/KR0	A
41	P06/WAIT	A
42	P05/CLKOUT	A
43	EV <sub>SS</sub>	I
44	P80/EX0	A
45	P81/EX1	A
46	P82/EX2	A
47	P83/EX3	A
48	P84/EX4	A
49	P85/EX5	A
50	P86/EX6	A

Table A-1. Target Interface Combinations (6/14)

KG3 (100GC) Pin Number	Pin Name in Target Device (78K0R/KX3)	Equivalent Circuit
51	P87/EX7	A
52	P30/INTP3/RTC1HZ	A
53	EV <sub>DD</sub>	D
54	P50/EX8	A
55	P51/EX9	A
56	P52/EX10	A
57	P53/EX11	A
58	P54/EX12	A
59	P55/EX13	A
60	P56/EX14	A
61	P57/EX15	A
62	P17/EX31/TI02/TO02	A
63	P16/EX30/TI01/TO01/INTP5	A
64	P15/EX29/RTCDIV/RTCCL	A
65	P14/EX28/RXD3	A
66	P13/EX27/TXD3	A
67	P12/EX26/SO00/TXD0	A
68	P11/EX25/SI00/RXD0	A
69	P10/EX24/SCK00	A
70	AV <sub>REF1</sub>	K
71	P110/ANO0	C
72	P111/ANO1	C
73	AV <sub>REF0</sub>	K
74	AV <sub>SS</sub>	I
75	P157/ANI15	B
76	P156/ANI14	B
77	P155/ANI13	B
78	P154/ANI12	B
79	P153/ANI11	B
80	P152/ANI10	B
81	P151/ANI9	B
82	P150/ANI8	B
83	P27/ANI7	B
84	P26/ANI6	B
85	P25/ANI5	B
86	P24/ANI4	B
87	P23/ANI3	B
88	P22/ANI2	B
89	P21/ANI1	B
90	P20/ANI0	B
91	P130	A
92	P131/TI06/TO06	A
93	P04/SCK10/SCL10	L
94	P03/SI10/RXD1/SDA10	L
95	P02/SO10/TXD1	A
96	P01/TO00	A
97	P00/TI00	A
98	P145/TI07/TO07	A
99	P144/SO20/TXD2	A
100	P143/SI20/RXD2/SDA20	L

Table A-1. Target Interface Combinations (7/14)

KG3 (100GF) Pin Number	Pin Name in Target Device (78K0R/KX3)	Equivalent Circuit
1	P60/SCL0	A
2	P61/SDA0	A
3	P62	A
4	P63	A
5	P31/TI03/TO03/INTP4	A
6	P64/RD	A
7	P65/WR0	A
8	P66/WR1	A
9	P67/ASTB	A
10	P77/EX23/KR7/INTP11	A
11	P76/EX22/KR6/INTP10	A
12	P75/EX21/KR5/INTP9	A
13	P74/EX20/KR4/INTP8	A
14	P73/EX19/KR3	A
15	P72/EX18/KR2	A
16	P71/EX17/KR1	A
17	P70/EX16/KR0	A
18	P06/WAIT	A
19	P05/CLKOUT	A
20	EV <sub>SS</sub>	I
21	P80/EX0	A
22	P81/EX1	A
23	P82/EX2	A
24	P83/EX3	A
25	P84/EX4	A
26	P85/EX5	A
27	P86/EX6	A
28	P87/EX7	A
29	P30/INTP3/RTC1HZ	A
30	EV <sub>DD</sub>	D
31	P50/EX8	A
32	P51/EX9	A
33	P52/EX10	A
34	P53/EX11	A
35	P54/EX12	A
36	P55/EX13	A
37	P56/EX14	A
38	P57/EX15	A
39	P17/EX31/TI02/TO02	A
40	P16/EX30/TI01/TO01/INTP5	A
41	P15/EX29/RTCDIV/RTCCL	A
42	P14/EX28/RXD3	A
43	P13/EX27/TXD3	A
44	P12/EX26/SO00/TXD0	A
45	P11/EX25/SI00/RXD0	A
46	P10/EX24/SCK00	A
47	AV <sub>REF1</sub>	K
48	P110/ANO0	C
49	P111/ANO1	C
50	AV <sub>REF0</sub>	K

Table A-1. Target Interface Combinations (8/14)

KG3 (100GF) Pin Number	Pin Name in Target Device (78K0R/KX3)	Equivalent Circuit
51	AV <sub>ss</sub>	I
52	P157/ANI15	B
53	P156/ANI14	B
54	P155/ANI13	B
55	P154/ANI12	B
56	P153/ANI11	B
57	P152/ANI10	B
58	P151/ANI9	B
59	P150/ANI8	B
60	P27/ANI7	B
61	P26/ANI6	B
62	P25/ANI5	B
63	P24/ANI4	B
64	P23/ANI3	B
65	P22/ANI2	B
66	P21/ANI1	B
67	P20/ANI0	B
68	P130	A
69	P131/TI06/TO06	A
70	P04/ $\overline{\text{SCK10}}$ /SCL10	L
71	P03/SI10/RXD1/SDA10	L
72	P02/SO10/TXD1	A
73	P01/TO00	A
74	P00/TI00	A
75	P145/TI07/TO07	A
76	P144/SO20/TXD2	A
77	P143/SI20/RXD2/SDA20	L
78	P142/ $\overline{\text{SCK20}}$ /SCL20	L
79	P141/PCLBUZ1/INTP7	A
80	P140/PCLBUZ0/INTP6	A
81	P120/INTP0/EXLVI	D
82	P47/INTP2	A
83	P46/INTP1/TI05/TO05	A
84	P45/SO01	A
85	P44/SI01	L
86	P43/ $\overline{\text{SCK01}}$	L
87	P42/TI04/TO04	A
88	P41/TOOL1	A
89	P40/TOOL0	A
90	$\overline{\text{RESET}}$	F
91	P124/XT2/EXCLKS	E
92	P123/XT1	A
93	FLMD0	G
94	P122/X2/EXCLK	E
95	P121/X1	A
96	REGC	J
97	V <sub>ss</sub>	H
98	EV <sub>ss</sub>	I
99	V <sub>DD</sub>	D
100	EV <sub>DD</sub>	D

**Table A-1. Target Interface Combinations (9/14)**

KH3 (128GF) Pin Number	Pin Name in Target Device (78K0R/KX3)	Equivalent Circuit
1	P142/SCK20/SCL20	L
2	P141/PCLBUZ1/INTP7	A
3	P140/PCLBUZ0/INTP6	A
4	P120/INTP0/EXLVI	D
5	P37	A
6	P36	A
7	P35	A
8	P34	A
9	P33	A
10	P32	A
11	P163/TI13/TO13	A
12	P162/TI12/TO12	A
13	P161/TI11/TO11	A
14	P160/TI10/TO10	A
15	P47/INTP2	A
16	P46/INTP1/TI05/TO05	A
17	P45/SO01	A
18	P44/SI01	L
19	P43/SCK01	L
20	P42/TI04/TO04	A
21	P41/TOOL1	A
22	P40/TOOL0	A
23	P127/SO21	A
24	P126/SI21/SDA21	L
25	P125/SCK21/SCL21	L
26	RESINB	F
27	P124/XT2/EXCLKS	E
28	P123/XT1	A
29	FLMD0/VPPTS1	G
30	P122/X2/EXCLK	E
31	P121/X1	A
32	REGC	J
33	V <sub>SS</sub>	H
34	EV <sub>SS0</sub>	I
35	V <sub>DD</sub>	D
36	EV <sub>DD0</sub>	D
37	P60/SCL0	A
38	P61/SDA0	A
39	P62	A
40	P63	A
41	P31/TI03/TO03/INTP4	A
42	P64/ $\overline{RD}$	A
43	P65/ $\overline{WR0}$	A
44	P66/ $\overline{WR1}$	A
45	P67/ASTB	A
46	P77/EX23/KR7/INTP11	A
47	P76/EX22/KR6/INTP10	A
48	P75/EX21/KR5/INTP9	A
49	P74/EX20/KR4/INTP8	A
50	P73/EX19/KR3	A

Table A-1. Target Interface Combinations (10/14)

KH3 (128GF) Pin Number	Pin Name in Target Device (78K0R/KX3)	Equivalent Circuit
51	P72/EX18/KR2	A
52	P71/EX17/KR1	A
53	P70/EX16/KR0	A
54	P06/ $\overline{\text{WAIT}}$	A
55	P05/CLKOUT	A
56	EV <sub>SS1</sub>	I
57	EV <sub>DD1E</sub>	D
58	P80/EX0	A
59	P81/EX1	A
60	P82/EX2	A
61	P83/EX3	A
62	P84/EX4	A
63	P85/EX5	A
64	P86/EX6	A
65	P87/EX7	A
66	P30/INTP3/RTC1HZ	A
67	P50/EX8	A
68	P51/EX9	A
69	P52/EX10	A
70	P53/EX11	A
71	P54/EX12	A
72	P55/EX13	A
73	P56/EX14	A
74	P57/EX15	A
75	P17/EX31/TI02	A
76	P16/EX30/TI01	A
77	P15/EX29/RTCDIV	A
78	P14/EX28/RXD3	A
79	P13/EX27/TXD3	A
80	P12/EX26/SO00	A
81	P11/EX25/SI00	A
82	P10/EX24/ $\overline{\text{SCK00}}$	A
83	P90/EX32	A
84	P91/EX33	A
85	P92/EX34	A
86	P93/EX35	A
87	P94	A
88	P95/ $\overline{\text{SCK11}}$	L
89	P96/SI11/SDA11	L
90	P97/SO11	A
91	P112	A
92	P113	A
93	P114	A
94	P115	A
95	P116	A
96	P117	A
97	AV <sub>REF1</sub>	K
98	P110/ANO0	C
99	P111/ANO1	C
100	AV <sub>REF0</sub>	K

**Table A-1. Target Interface Combinations (11/14)**

KH3 (128GF) Pin Number	Pin Name in Target Device (78K0R/KX3)	Equivalent Circuit
101	AV <sub>SS0</sub>	I
102	P157/ANI15	B
103	P156/ANI14	B
104	P155/ANI13	B
105	P154/ANI12	B
106	P153/ANI11	B
107	P152/ANI10	B
108	P151/ANI9	B
109	P150/ANI8	B
110	P27/ANI7	B
111	P26/ANI6	B
112	P25/ANI5	B
113	P24/ANI4	B
114	P23/ANI3	B
115	P22/ANI2	B
116	P21/ANI1	B
117	P20/ANI0	B
118	P130	A
119	P131/TI06/TO06	A
120	P07	A
121	P04/SCK10/SCL10	L
122	P03/SI10/RXD1/SDA10	L
123	P02/SO10/TXD1	A
124	P01/TO00	A
125	P00/TI00	A
126	P145/TI07/TO07	A
127	P144/SO20/TXD2	A
128	P143/SI20/RXD2/SDA20	L

Table A-1. Target Interface Combinations (12/14)

KJ3 (144GJ) Pin Number	Pin Name in Target Device (78K0R/KX3)	Equivalent Circuit
1	P141/PCLBUZ1/INTP7	A
2	P140/PCLBUZ0/INTP6	A
3	P120/INTP0/EXLVI	D
4	P37	A
5	P36	A
6	P35	A
7	P34	A
8	P33	A
9	P32	A
10	P163/TI13/TO13	A
11	P162/TI12/TO12	A
12	P161/TI11/TO11	A
13	P160/TI10/TO10	A
14	P47/INTP2	A
15	P46/INTP1/TI05/TO05	A
16	P45/SO01	A
17	P44/SI01	L
18	P43/SCK01	L
19	P42/TI04/TO04	A
20	P41/TOOL1	A
21	P40/TOOL0	A
22	P127/SO21	A
23	P126/SI21/SDA21	L
24	P125/SCK21/SCL21	L
25	RESINB	F
26	P124/XT2/EXCLKS	E
27	P123/XT1	A
28	FLMD0/VPPTS1	G
29	P122/X2/EXCLK	E
30	P121/X1	A
31	REGC	J
32	V <sub>SS</sub>	H
33	EV <sub>SS0</sub>	I
34	V <sub>DD</sub>	D
35	EV <sub>DD0</sub>	D
36	P60/SCL0	A
37	P61/SDA0	A
38	P62	A
39	P63	A
40	P100	A
41	P101	A
42	P102	A
43	P103	A
44	P104	A
45	P105	A
46	P106	A
47	P107	A
48	P31/TI03/TO03/INTP4	A
49	P64/ $\overline{RD}$	A
50	P65/ $\overline{WR0}$	A

**Table A-1. Target Interface Combinations (13/14)**

KJ3 (144GJ) Pin Number	Pin Name in Target Device (78K0R/KX3)	Equivalent Circuit
51	P66/ $\overline{WR1}$	A
52	P67/ASTB	A
53	P77/EX23/KR7/INTP11	A
54	P76/EX22/KR6/INTP10	A
55	P75/EX21/KR5/INTP9	A
56	P74/EX20/KR4/INTP8	A
57	P73/EX19/KR3	A
58	P72/EX18/KR2	A
59	P71/EX17/KR1	A
60	P70/EX16/KR0	A
61	P06/ $\overline{WAIT}$	A
62	P05/CLKOUT	A
63	EV <sub>SS1</sub>	I
64	EV <sub>DD1E</sub>	D
65	P80/EX0	A
66	P81/EX1	A
67	P82/EX2	A
68	P83/EX3	A
69	P84/EX4	A
70	P85/EX5	A
71	P86/EX6	A
72	P87/EX7	A
73	P30/INTP3/RTC1HZ	A
74	P50/EX8	A
75	P51/EX9	A
76	P52/EX10	A
77	P53/EX11	A
78	P54/EX12	A
79	P55/EX13	A
80	P56/EX14	A
81	P57/EX15	A
82	P17/EX31/TI02/TO02	A
83	P16/EX30/TI01/TO01/INTP5	A
84	P15/EX29/RTCDIV/RTCCL	A
85	P14/EX28/RXD3	A
86	P13/EX27/TXD3	A
87	P12/EX26/SO00/TXD0	A
88	P11/EX25/SI00/RXD0	A
89	P10/EX24/ $\overline{SCK00}$	A
90	P90/EX32	A
91	P91/EX33	A
92	P92/EX34	A
93	P93/EX35	A
94	P94	A
95	P95/ $\overline{SCK11}$ /SCL11	L
96	P96/SI11/SDA11	L
97	P97/SO11	A
98	P112	A
99	P113	A
100	P114	A

Table A-1. Target Interface Combinations (14/14)

KJ3 (144GJ) Pin Number	Pin Name in Target Device (78K0R/KX3)	Equivalent Circuit
101	P115	A
102	P116	A
103	P117	A
104	AV <sub>REF1</sub>	K
105	P110/ANO0	C
106	P111/ANO1	C
107	AV <sub>REF0</sub>	K
108	AV <sub>SS0</sub>	I
109	P157/ANI15	B
110	P156/ANI14	B
111	P155/ANI13	B
112	P154/ANI12	B
113	P153/ANI11	B
114	P152/ANI10	B
115	P151/ANI9	B
116	P150/ANI8	B
117	P27/ANI7	B
118	P26/ANI6	B
119	P25/ANI5	B
120	P24/ANI4	B
121	P23/ANI3	B
122	P22/ANI2	B
123	P21/ANI1	B
124	P20/ANI0	B
125	P130	A
126	P131/TI06/TO06	A
127	P132	A
128	P133	A
129	P134	A
130	P135	A
131	P136	A
132	P137	A
133	P07	A
134	P04/SCK10/SCL10	L
135	P03/SI10/RXD1/SDA10	L
136	P02/SO10/TXD1	A
137	P01/TO00	A
138	P00/TI00	A
139	P147	A
140	P146	A
141	P145/TI07/TO07	A
142	P144/SO20/TXD2	A
143	P143/SI20/RXD2/SDA20	L
144	P142/SCK20/SCL20	L

## APPENDIX B REVISION HISTORY

## B.1 Major Revisions in This Edition

Page	Description
<b>INTRODUCTION</b>	
p.7	Change of Documents Related to Development Tools (User's Manuals)
<b>CHAPTER 1 GENERAL</b>	
p. 10	Change of the value target system power supply in Power consumption description in <b>Table 1-1. QB-78K0RKX3 Hardware Specifications</b> Current: approx. 17 mA MAX.→ approx. 4.1 mA MAX.
p.13	Deletion of descriptions "sold separately" and <b>Notes in Table 1-3. Adapters and Connectors for Each Target Device, Table 1-4. Common Probe and Adapter</b> Change of decription
p. 14	Change of descriptions in <b>1.5 Package Contents</b>
<b>CHAPTER 2 SETUP PROCEDURE</b>	
p.20	Change of description in <b>2. 3 Clock Settings</b>
p.25	Change of description in <b>2.5.2 Mounting YQ to TC</b>
<b>CHAPTER 4 CAUTIONS</b>	
p. 33 to 34	Addition of <b>CHAPTER 4 CAUTIONS</b>
<b>APPENDIX B REVISION HISTORY</b>	
p. 55	Updating of description

**B.2 Revision History of Preceding Editions**

Edition	Major Revision from Previous Edition	Applied to:
3rd edition	Addition of 78K0R/KH3 and 78K0R/KJ3 to target devices	throughout
	Change of description in <b>1.3 System Configuration</b>	<b>CHAPTER 1 GENERAL</b>
	Change of description of <1> Host machine in <b>Figure 1-1. System Configuration</b>	
	Addition of 78K0R/KH3 and 78K0R/KJ3 in and addition of description in Note 1 of <b>Table 1-3. Adapters and Connectors for Each Target Device</b>	
	Addition of description in <b>1.5 Package Contents</b>	
	Addition of KH3 and KJ3 in <b>Table A-1. Target Interface Combinations</b>	<b>APPENDIX A CHARACTERISTICS OF TARGET INTERFACE</b>
Addition of <b>APPENDIX B REVISION HISTORY</b>	<b>APPENDIX B REVISION HISTORY</b>	
2nd edition	Addition of 78K0R/KE3 to target devices	throughout
	<b>Table 1-1. QB-78K0RKX3 Hardware Specifications</b> <ul style="list-style-type: none"> <li>• Change of power consumption (AC adapter for QB-78K0RKX3)</li> <li>• Change of figure</li> </ul>	<b>CHAPTER 1 GENERAL</b>
	Change of <b>Table 1-2. QB-78K0RKX3 System Specifications</b>	
	Change of <b>Figure 1-1. System Configuration</b>	
	Deletion of <b>1.3 Target Devices</b>	
	<b>1.4 System Configuration for Each Target Device</b> <ul style="list-style-type: none"> <li>• Change of <b>Note 1</b></li> <li>• Change of <b>Remark</b></li> </ul>	
	Change of description in <b>1.5 Package Contents</b>	
	Change of <b>Figure 2-1. Names of Parts of QB-78K0RKX3</b>	<b>CHAPTER 2 SETUP PROCEDURE</b>
	Change of <b>Figure 2-2. Acrylic Board Removal Method</b>	
	<b>2.5.1 Mounting TC to target system</b> <ul style="list-style-type: none"> <li>• Change of (3) - Soldering conditions</li> </ul>	
	Change of description in <b>2.5.4 Precautions for handling TC, YQ, SA, and CA</b>	
	Change of <b>Figure 2-5. Using Probe Holder</b>	
	Change of <b>Figure 2-6. GND Wire</b>	
	Change of <b>Figure 2-7. Where GND Wire Can Be Connected</b>	
	Change of <b>Figure 2-8. Connection Using Emulation Probe</b>	
	Change of <b>Figure 2-9. Connector Positions</b>	
	Deletion of <b>Figure 2-10. AC Plugs</b>	
	Change of <b>Figure A-1. Equivalent Circuit of Target Interface</b>	<b>APPENDIX A CHARACTERISTICS OF TARGET INTERFACE</b>
	Change of <b>Table A-1. Target Interface Combinations</b>	
	Deletion of <b>APPENDIX B NOTES ON TARGET SYSTEM DESIGN</b>	throughout
	Deletion of <b>APPENDIX C PACKAGE DRAWINGS</b>	
Deletion of <b>APPENDIX D PIN HEADER COVER MOUNTING METHODS</b>		
Addition of <b>APPENDIX B REVISION HISTORY</b>		

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